

最终数据表

英飞凌CoolSiC™ 1200 V SiC 沟道MOSFET

特性

- $T_{vj} = -55...175^{\circ}\text{C}$ 时 $T_{DSS} = 1200\text{ V}$
- $T_C = 25^{\circ}\text{C}$ 时 $I_{DDC} = 100\text{ A}$
- $R_{DS(on)} = 19\text{ m}\Omega$ ($V_{GS} = 20\text{ V}$ 、 $T_{vj} = 25^{\circ}\text{C}$ 时)
- 新的性能优化芯片技术 (Gen1p)，改善了 $R_{DS(on)} \cdot A$
- 提高了建议开启电压 ($V_{GS(on)} = 20\text{ V}$) 以降低 $R_{DS(on)}$
- 业界领先的开关能量特性，可降低开关损耗并减少冷却需求
- 最低的器件电容值，可实现更高的开关速度和更高的功率密度
- 低 C_{rss}/C_{iss} 电容比值和高 $V_{GS(th)}$ 的组合，可避免寄生导通并实现单极性栅极驱动
- 降低了总栅极电荷 Q_G ，可降低驱动功率和损耗
- .XT 芯片粘接技术，实现业界领先的热性能
- 用于优化开关性能的检测引脚
- 适合高压爬电要求

潜在应用

- 车载充电器
- 直流/直流转换器
- 辅助驱动

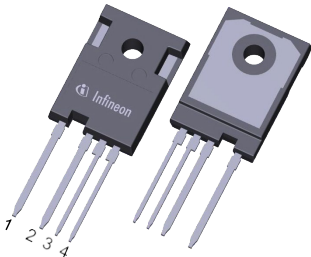
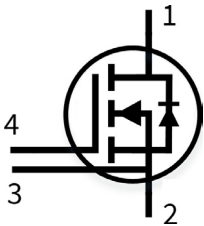
产品验证

- 适合汽车应用。根据 AEC-Q100/101 进行产品验证

描述

引脚定义：

- 1 - 漏极
- 2 - 来源
- 3 - 开尔文检测
- 4 - 栅极



Type	Package	Marking
AIMZH120R020M1T	PG-TO247-4-STD-NT6.7	A12M1T020

本数据手册的原文使用英文撰写。为方便起见，英飞凌提供了译文；由于翻译过程中可能使用了自动化工具，英飞凌不保证译文的准确性。为确认准确性，请务必访问 infineon.com 参考最新的英文版本（控制文档）。



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1 封装

1 封装

表1 特征值

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}				260	°C
MOSFET/body diode thermal resistance, junction-case	$R_{\text{th(j-c)}}$			0.27	0.35	K/W

注释: 无需经过生产测试 - 经过设计/特性验证

2 MOSFET

表2 最大额定值

Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage	V_{DSS}	$T_{\text{vj}} = -55 \dots 175 \text{ °C}$		1200	V
Continuous DC drain current for $R_{\text{th(j-c,max)}}$, limited by $T_{\text{vj(max)}}$	I_{DDC}	$V_{\text{GS}} = 20 \text{ V}$	$T_{\text{c}} = 25 \text{ °C}$	100	A
			$T_{\text{c}} = 100 \text{ °C}$	71	
Peak drain current, t_{p} limited by $T_{\text{vj(max)}}$	I_{DM}	$V_{\text{GS}} = 20 \text{ V}$		256	A
Gate-source voltage, max. transient voltage ¹⁾	V_{GS}	$t_{\text{p}} \leq 0.5 \text{ }\mu\text{s}, D < 0.01$		-10...25	V
Gate-source voltage, max. static voltage	V_{GS}			-5...23	V
Avalanche energy, single pulse	E_{AS}	$I_{\text{D}} = 32 \text{ A}, V_{\text{DD}} = 50 \text{ V}, L = 0.67 \text{ mH}$		340	mJ
Power dissipation, limited by $T_{\text{vj(max)}}$	P_{tot}		$T_{\text{c}} = 25 \text{ °C}$	429	W
			$T_{\text{c}} = 100 \text{ °C}$	214	

1) **重要注释:** 正负栅极源电压的选择会影响器件的长期行为。为了确保器件在计划使用寿命内的正常运行，必须考虑应用说明AN2018-09中描述的设计指南。

表 3 建议值

Parameter	Symbol	Note or test condition	Values	Unit
Recommended turn-on gate voltage	$V_{\text{GS(on)}}$		20	V
Recommended turn-off gate voltage	$V_{\text{GS(off)}}$		0	V

表4 特征值

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Drain-source on-state resistance	$R_{DS(on)}$	$I_D = 43\text{ A}$	$T_{vj} = 25\text{ °C}$, $V_{GS(on)} = 20\text{ V}$		19	25	mΩ
			$T_{vj} = 100\text{ °C}$, $V_{GS(on)} = 20\text{ V}$		27		
			$T_{vj} = 175\text{ °C}$, $V_{GS(on)} = 20\text{ V}$		38		
			$T_{vj} = 25\text{ °C}$, $V_{GS(on)} = 18\text{ V}$		20.6		
Gate-source threshold voltage	$V_{GS(th)}$	$I_D = 13.7\text{ mA}$, $V_{DS} = V_{GS}$ (tested after 1 ms pulse at $V_{GS} = 20\text{ V}$)	$T_{vj} = 25\text{ °C}$	3.5	4.3	5.1	V
			$T_{vj} = 175\text{ °C}$		3.8		
Zero gate-voltage drain current	I_{DSS}	$V_{DS} = 1200\text{ V}$, $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$		0.6	42	μA
			$T_{vj} = 175\text{ °C}$		50		
Gate leakage current	I_{GSS}	$V_{DS} = 0\text{ V}$	$V_{GS} = 25\text{ V}$			100	nA
			$V_{GS} = -10\text{ V}$			-100	
Forward transconductance	g_{fs}	$I_D = 43\text{ A}$, $V_{DS} = 20\text{ V}$			27		S
Short-circuit withstand time ¹⁾	t_{SC}	$V_{DD} \leq 800\text{ V}$, $V_{DS,peak} < 1200\text{ V}$, $T_{vj(start)} = 25\text{ °C}$, $R_{G,ext} = 2\text{ Ω}$	$V_{GS(on)} = 20\text{ V}$		1.5		μs
			$V_{GS(on)} = 18\text{ V}$		2		
			$V_{GS(on)} = 15\text{ V}$		2.5		
Internal gate resistance	$R_{G,int}$	$f = 1\text{ MHz}$, $V_{AC} = 25\text{ mV}$			2.2		Ω
Input capacitance	C_{iss}	$V_{DD} = 800\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$			2667		pF
Output capacitance	C_{oss}	$V_{DD} = 800\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$			126		pF
Reverse transfer capacitance	C_{rss}	$V_{DD} = 800\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$			7		pF
C_{oss} stored energy	E_{oss}	$V_{DD} = 800\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$			52		μJ
Total gate charge	Q_G	$V_{DD} = 800\text{ V}$, $I_D = 43\text{ A}$, $V_{GS} = 0/20\text{ V}$, turn-on pulse			82		nC
Plateau gate charge	$Q_{GS(pl)}$	$V_{DD} = 800\text{ V}$, $I_D = 43\text{ A}$, $V_{GS} = 0/20\text{ V}$, turn-on pulse			22		nC
Gate-to-drain charge	Q_{GD}	$V_{DD} = 800\text{ V}$, $I_D = 43\text{ A}$, $V_{GS} = 0/20\text{ V}$, turn-on pulse			14		nC
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 800\text{ V}$, $I_D = 43\text{ A}$, $V_{GS} = 0/20\text{ V}$, $R_{GS(on)} = 2\text{ Ω}$, $R_{GS(off)} = 2\text{ Ω}$, $L_\sigma = 15\text{ nH}$	$T_{vj} = 25\text{ °C}$		13		ns
			$T_{vj} = 175\text{ °C}$		13		

(表格续下页.....)



表 4（续） 特征值

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Rise time	t_r	$V_{DD} = 800\text{ V}, I_D = 43\text{ A},$ $V_{GS} = 0/20\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH}$	$T_{vj} = 25\text{ }^\circ\text{C}$		11		ns
			$T_{vj} = 175\text{ }^\circ\text{C}$		16		
Turn-off delay time	$t_{d(off)}$	$V_{DD} = 800\text{ V}, I_D = 43\text{ A},$ $V_{GS} = 0/20\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH}$	$T_{vj} = 25\text{ }^\circ\text{C}$		27		ns
			$T_{vj} = 175\text{ }^\circ\text{C}$		31		
Fall time	t_f	$V_{DD} = 800\text{ V}, I_D = 43\text{ A},$ $V_{GS} = 0/20\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH}$	$T_{vj} = 25\text{ }^\circ\text{C}$		8		ns
			$T_{vj} = 175\text{ }^\circ\text{C}$		9		
Turn-on energy	E_{on}	$V_{DD} = 800\text{ V}, I_D = 43\text{ A},$ $V_{GS} = 0/20\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH}$	$T_{vj} = 25\text{ }^\circ\text{C}$		283		μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$		468		
Turn-off energy	E_{off}	$V_{DD} = 800\text{ V}, I_D = 43\text{ A},$ $V_{GS} = 0/20\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH}$	$T_{vj} = 25\text{ }^\circ\text{C}$		145		μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$		164		
Total switching energy	E_{tot}	$V_{DD} = 800\text{ V}, I_D = 43\text{ A},$ $V_{GS} = 0/20\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH}$	$T_{vj} = 25\text{ }^\circ\text{C}$		428		μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$		632		
Virtual junction temperature	T_{vj}			-55		175	$^\circ\text{C}$

1)通过设计/特性验证

注释：动态测试电路见图F。

3 体二极管（MOSFET）

表5 最大额定值

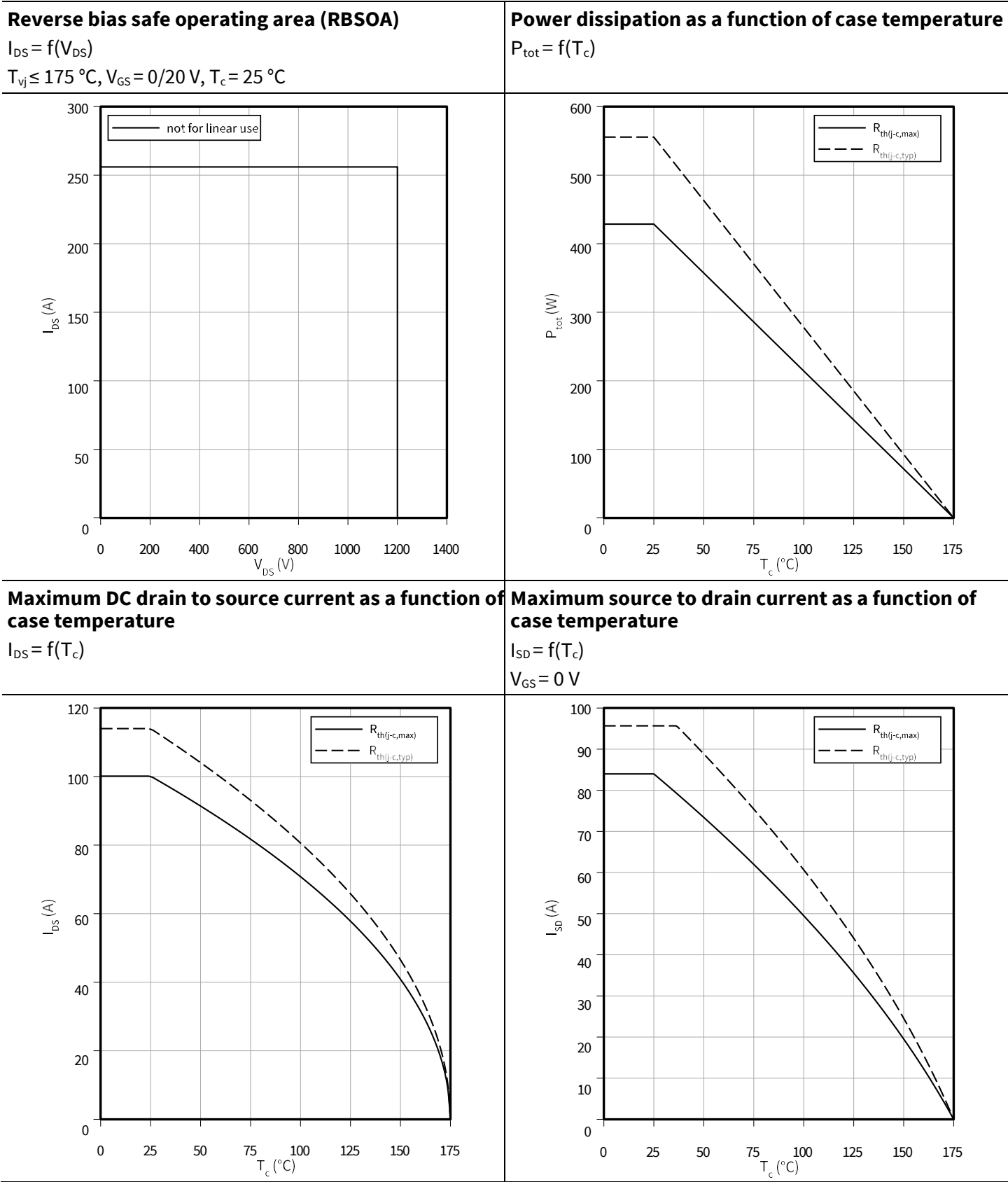
Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage	V_{DSS}	$T_{vj} = -55...175\text{ }^\circ\text{C}$		1200	V
Continuous reverse drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$	I_{SDC}	$V_{GS} = 0\text{ V}$	$T_c = 25\text{ }^\circ\text{C}$	83	A
			$T_c = 100\text{ }^\circ\text{C}$	49	
Peak reverse drain current, t_p limited by $T_{vj(max)}$	I_{SM}	$V_{GS} = 0\text{ V}$		95	A



表6特征值

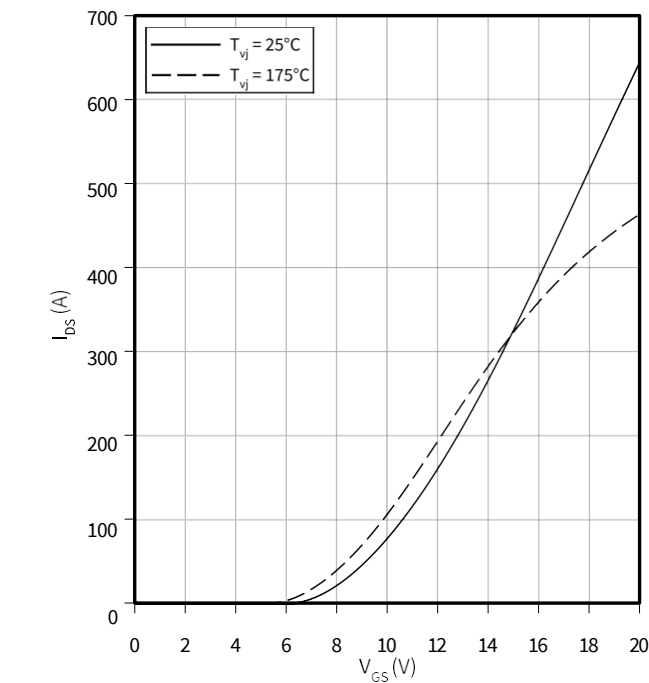
Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Drain-source reverse voltage	V_{SD}	$I_{SD} = 43\text{ A}$, $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$		3.9	5	V
			$T_{vj} = 100\text{ °C}$		3.8		
			$T_{vj} = 175\text{ °C}$		3.7		
MOSFET forward recovery charge	Q_{fr}	$V_{DD} = 800\text{ V}$, $I_{SD} = 43\text{ A}$, $V_{GS} = 0\text{ V}$, $di_{SD}/dt = 3000\text{ A}/\mu\text{s}$, Q_{fr} includes also Q_C	$T_{vj} = 25\text{ °C}$		290		nC
			$T_{vj} = 175\text{ °C}$		643		
MOSFET peak forward recovery current	I_{frm}	$V_{DD} = 800\text{ V}$, $I_{SD} = 43\text{ A}$, $V_{GS} = 0\text{ V}$, $di_{SD}/dt = 3000\text{ A}/\mu\text{s}$, Q_{fr} includes also Q_C	$T_{vj} = 25\text{ °C}$		10		A
			$T_{vj} = 175\text{ °C}$		30		
Virtual junction temperature	T_{vj}			-55		175	°C

4 特性图



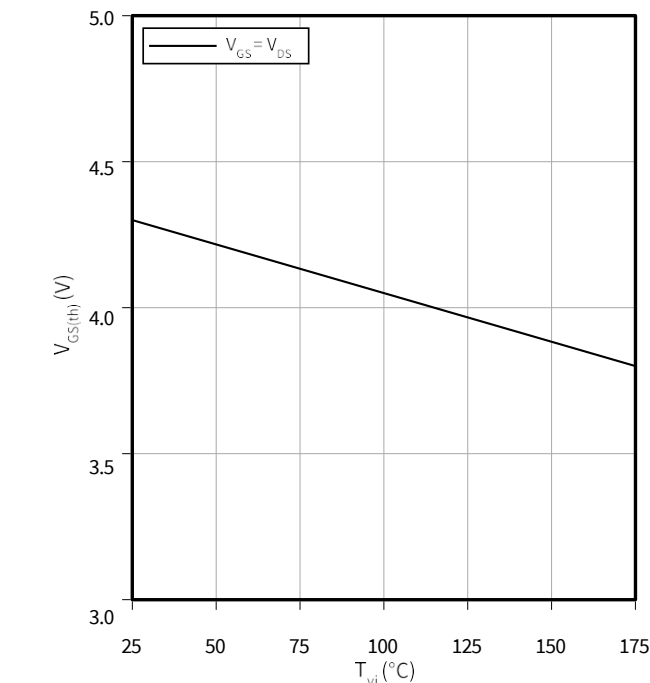
Typical transfer characteristic

$I_{DS} = f(V_{GS})$
 $V_{DS} = 20\text{ V}$



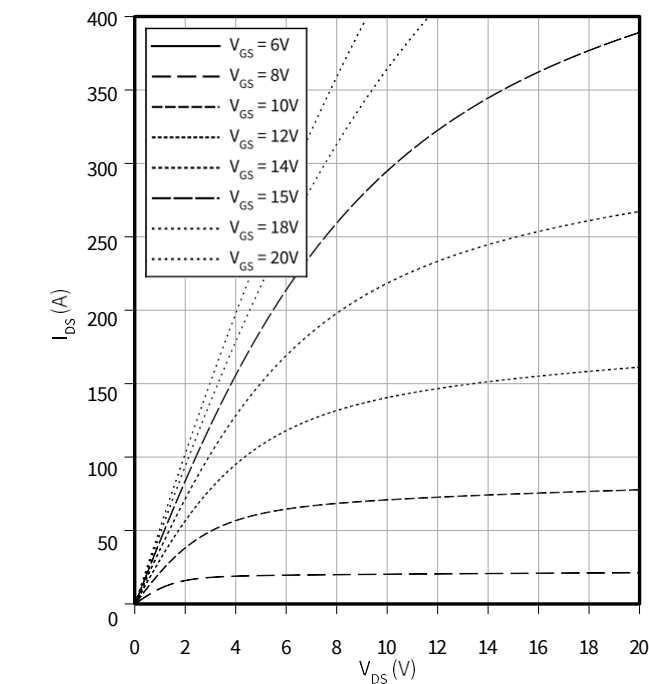
Typical gate-source threshold voltage as a function of junction temperature

$V_{GS(th)} = f(T_{vj})$
 $I_D = 13.7\text{ mA}$



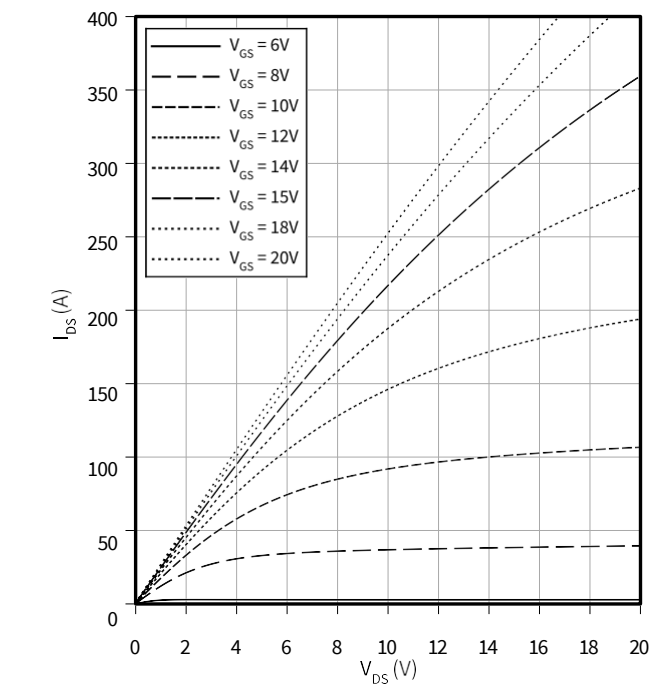
Typical output characteristic, V_{GS} as parameter

$I_{DS} = f(V_{DS})$
 $T_{vj} = 25\text{ }^\circ\text{C}$



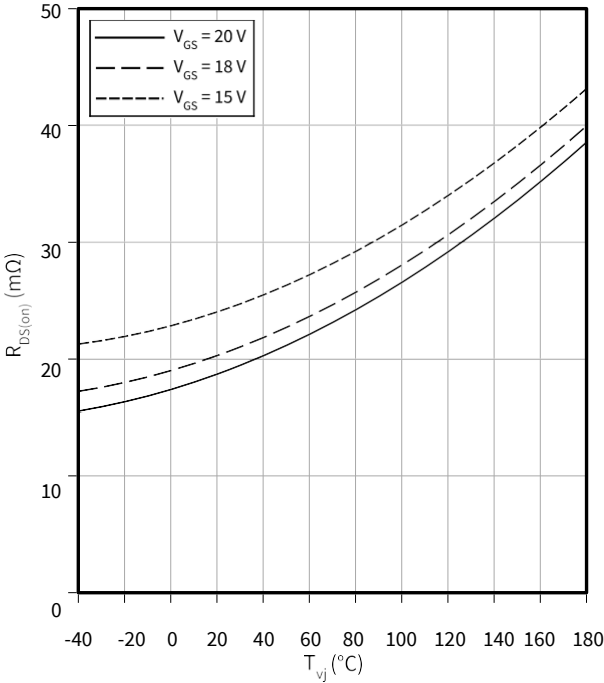
Typical output characteristic, V_{GS} as parameter

$I_{DS} = f(V_{DS})$
 $T_{vj} = 175\text{ }^\circ\text{C}$



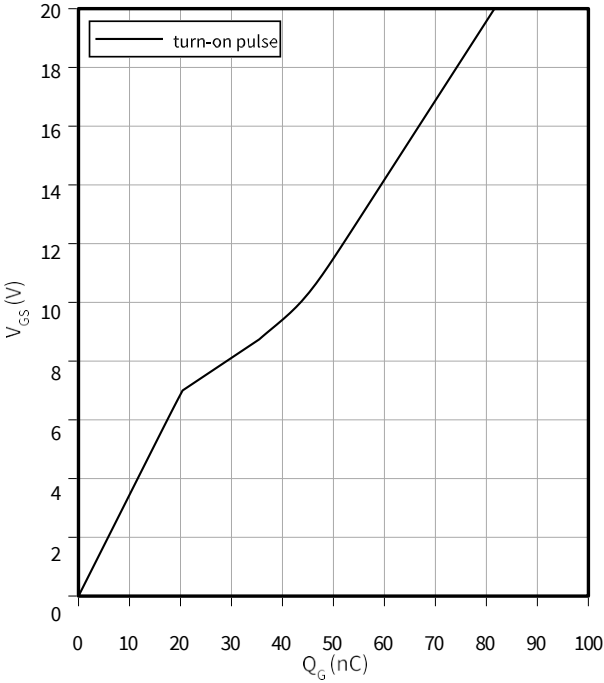
Typical on-state resistance as a function of junction temperature

$R_{DS(on)} = f(T_{vj})$
 $I_D = 43\text{ A}$



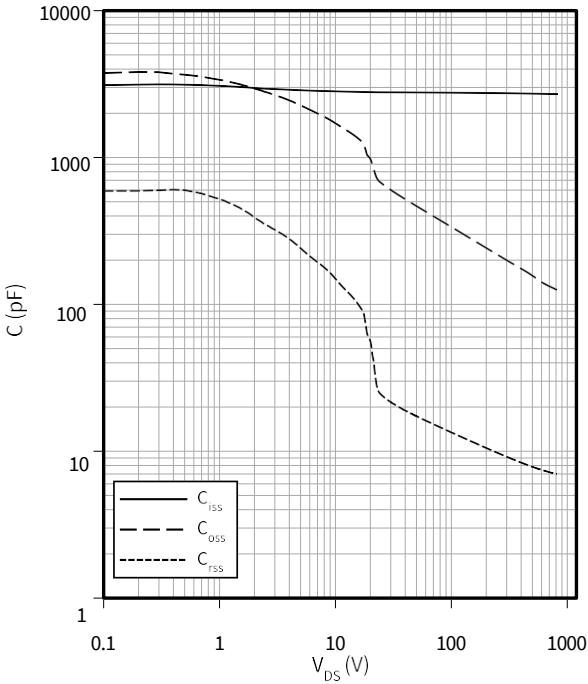
Typical gate charge

$V_{GS} = f(Q_G)$
 $I_D = 43\text{ A}, V_{DS} = 800\text{ V}$



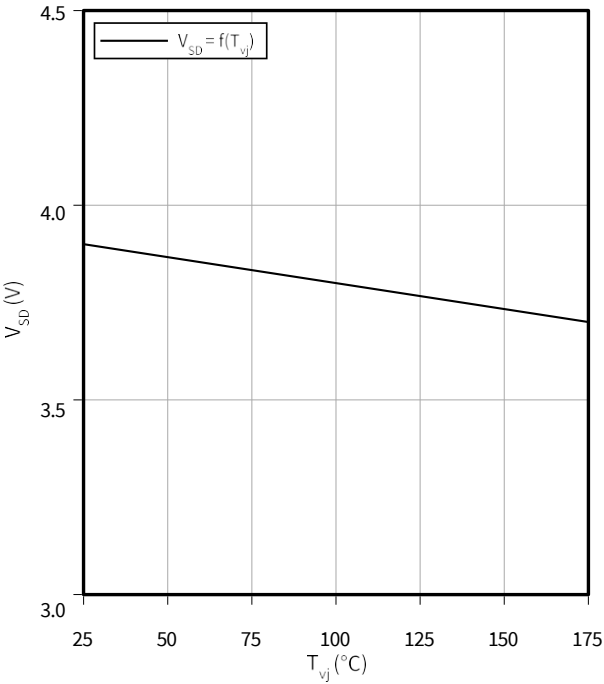
Typical capacitance as a function of drain-source voltage

$C = f(V_{DS})$
 $f = 100\text{ kHz}, V_{GS} = 0\text{ V}$



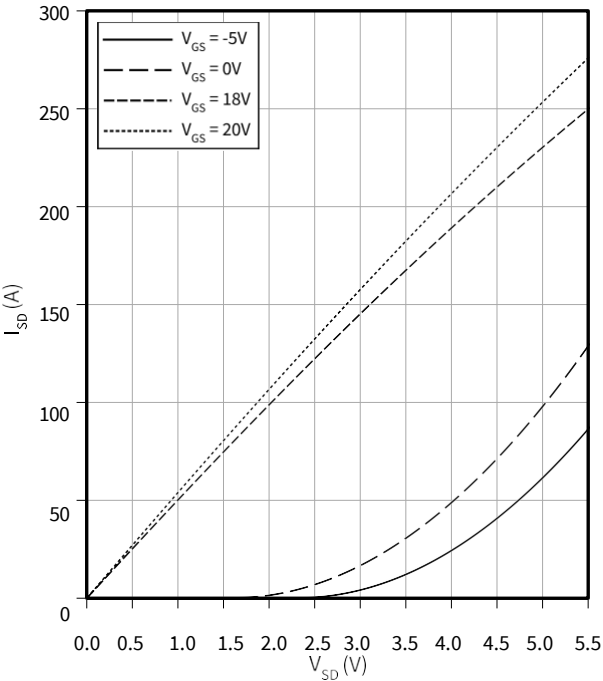
Typical reverse drain voltage as function of junction temperature

$V_{SD} = f(T_{vj})$
 $I_{SD} = 43\text{ A}, V_{GS} = 0\text{ V}$



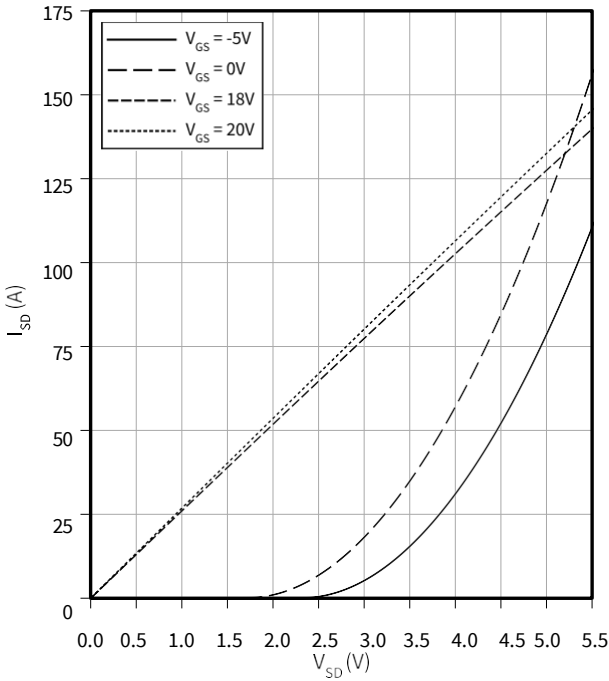
Typical reverse drain current as function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 25\text{ }^{\circ}\text{C}$



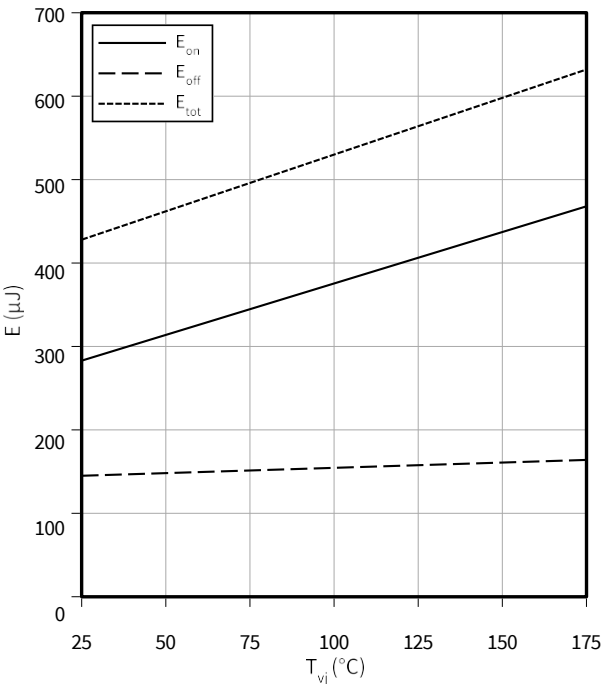
Typical reverse drain current as function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 175\text{ }^{\circ}\text{C}$



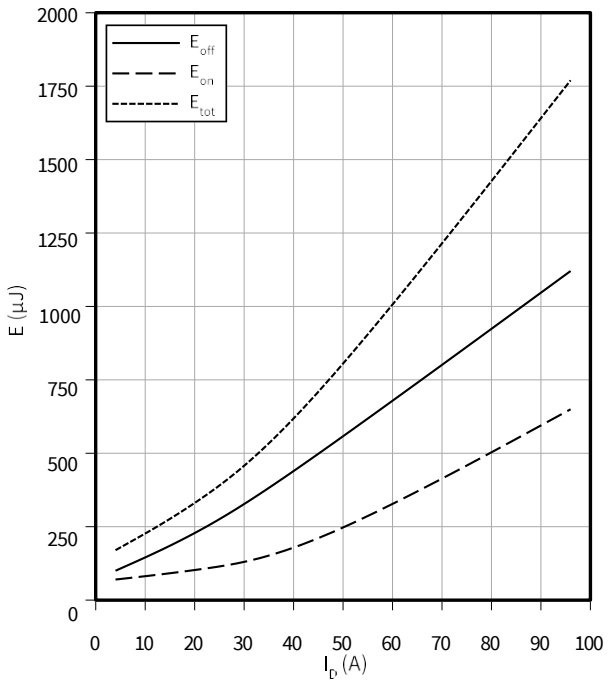
Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(T_{vj})$
 $V_{GS} = 0/20\text{ V}$, $I_D = 43\text{ A}$, $R_{G,ext} = 2\text{ }\Omega$, $V_{DD} = 800\text{ V}$



Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

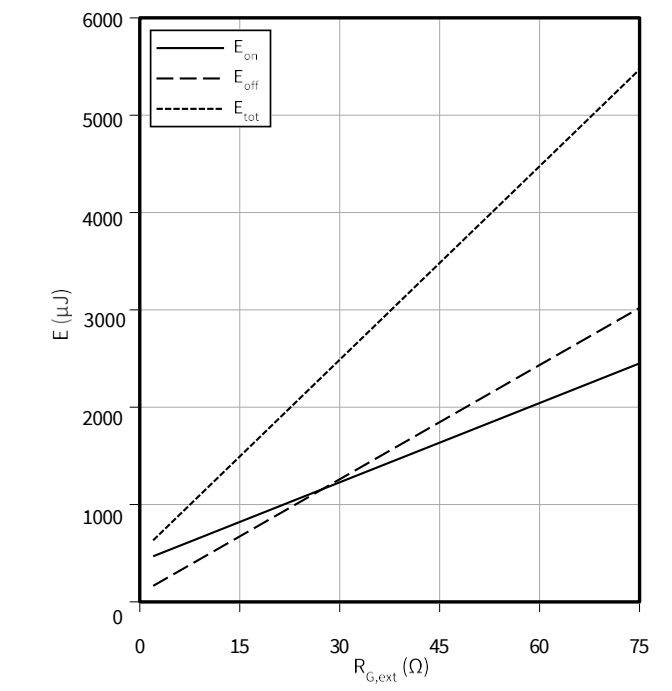
$E = f(I_D)$
 $V_{GS} = 0/20\text{ V}$, $T_{vj} = 175\text{ }^{\circ}\text{C}$, $R_{G,ext} = 2\text{ }\Omega$, $V_{DD} = 800\text{ V}$



Typical switching energy as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(R_{G,ext})$

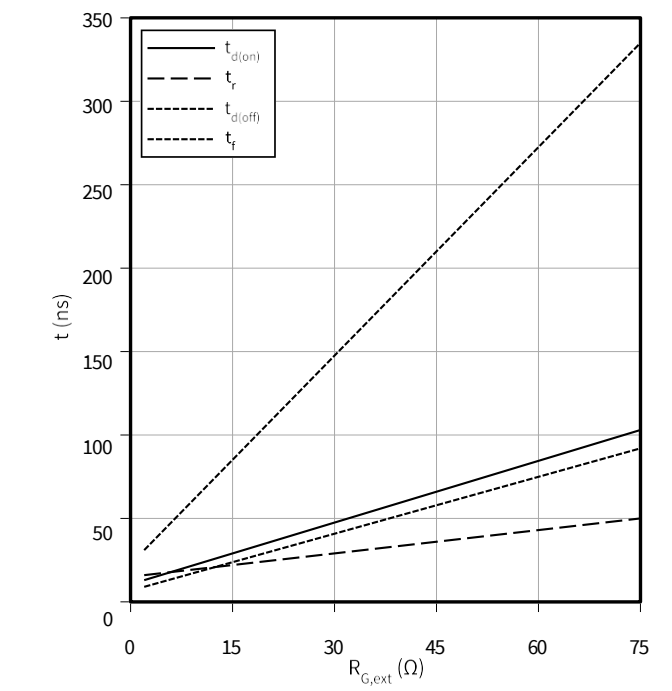
$V_{GS} = 0/20\text{ V}$, $I_D = 43\text{ A}$, $T_{vj} = 175\text{ }^{\circ}\text{C}$, $V_{DD} = 800\text{ V}$



Typical switching times as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$t = f(R_{G,ext})$

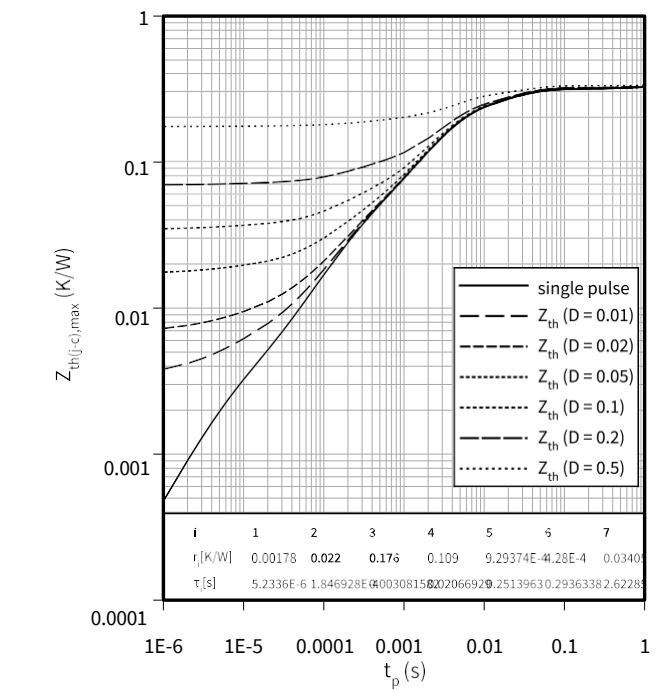
$V_{GS} = 0/20\text{ V}$, $I_D = 43\text{ A}$, $T_{vj} = 175\text{ }^{\circ}\text{C}$, $V_{DD} = 800\text{ V}$



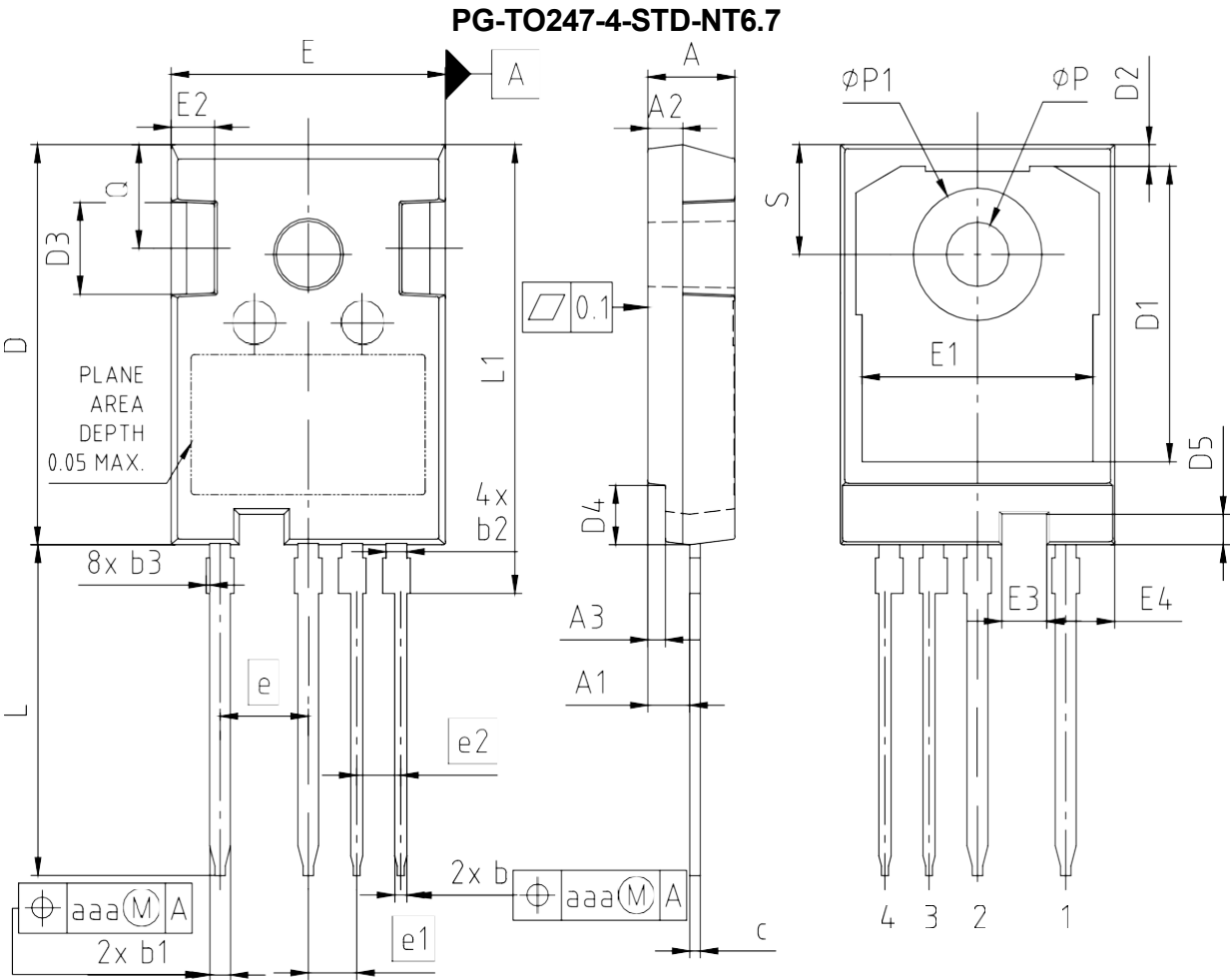
Max. transient thermal impedance (MOSFET/diode)

$Z_{th(j-c),max} = f(t_p)$

$D = t_p/T$



5 封装外形



PACKAGE - GROUP NUMBER: PG-TO247-4-U03

DIMENSIONS	MILLIMETERS		DIMENSIONS	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	4.90	5.10	E	15.70	15.90
A1	2.31	2.51	E1	13.10	13.50
A2	1.90	2.10	E2	2.40	2.60
A3	0.90	1.10	E3	2.48	2.68
b	0.66	0.79	E4	3.82	4.02
b1	1.16	1.29	e	5.08	
b2	1.16	1.29	e1	2.79	
b3		0.20	e2	2.54	
c	0.59	0.66	N	4	
D	22.30	22.50	L	18.40	18.70
D1	16.25	16.85	L1	24.97	25.27
D2	1.05	1.35	øP	3.50	3.70
D3	5.00	5.20	øP1		7.40
D4	3.22	3.42	Q	5.60	6.00
D5	1.60	1.80	S	6.00	6.30
			aaa	0.25	

NOTE: DIMENSIONS DO NOT INCLUDE MOLDFLASH, PROTRUSION OR GARE BURRS

图 1

6 测试条件

6 测试条件

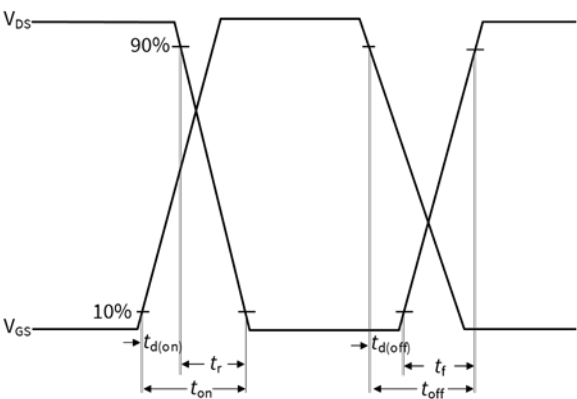


Figure A. Definition of switching times

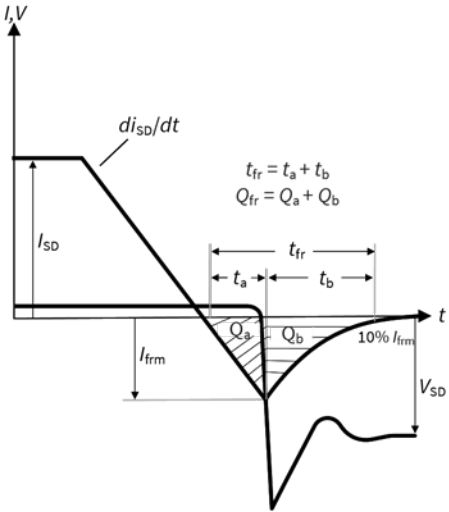


Figure B. Definition of body diode switching characteristics

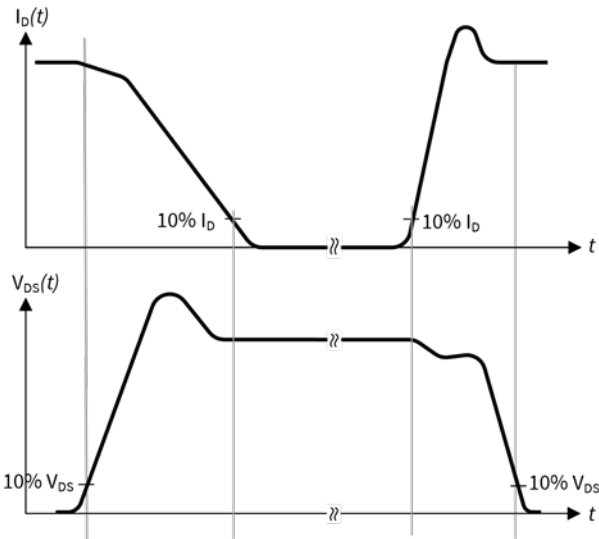


Figure C. Definition of switching losses

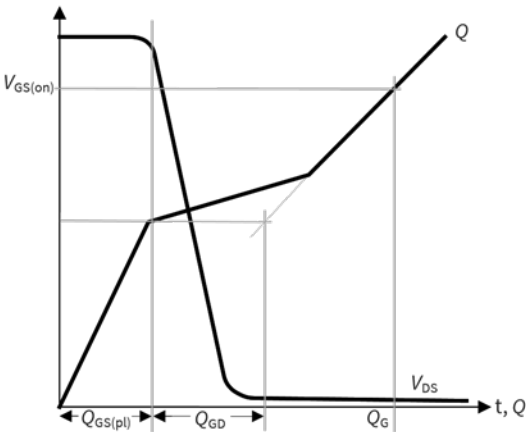


Figure D. Definition of QGD

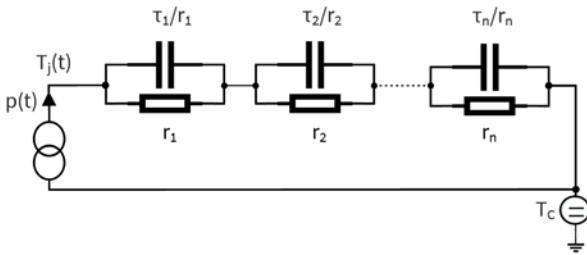


Figure E. Thermal equivalent circuit

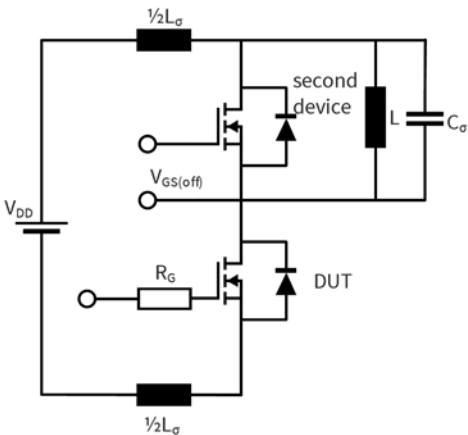


Figure F. Dynamic test circuit
Parasitic inductance L_σ ,
Parasitic capacitor C_σ ,

图 2



修订记录

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Document revision	Date of release	Description of changes
0.10	2022-04-19	Target datasheet
0.20	2023-07-31	Preliminary datasheet
0.30	2023-08-03	Correction of inductance unit (p. 3) Correction of diagram template E(Id)
1.00	2023-11-29	Final datasheet



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